



Semiconductor Equipment Association of Japan

June 2026 Billings (Express Report)

Japan-based Semiconductor Manufacturing Equipment

Note : All data is based on three month average numbers.

Mark your calendars. **The July Report SEAJ's Web site update** is scheduled on **21st August** approximately 3:40P.M.Japan Time. Up dates are subject to change.

Japanese Semiconductor Equipment Industry Posts **June 2026 Billings of ¥513,610 million**

Tokyo Japan, **July 21st, 2026** JAPAN-based manufacturers of semiconductor equipment posted **¥513,610 million** in billings in **June 2026**(three-month average basis) published today by SEAJ.

The billings figure is **2.4 percent down** the final **May 2026** level of **¥526,352 million** and **26.9 percent up** the **2025 June** billings level of **¥404,592 million**.

The SEAJ billings are three-month moving average billings for the Japanese semiconductor equipment industry. Billings figures are in millions of Japanese ¥.

	Billings (Three-month avg.)	Month-Over-Month	Year-Over-Year
January 2026	427,508	0.9%	2.6%
February 2026	423,103	-1.0%	2.7%
March 2026	480,182	13.5%	11.1%
April 2026	510,155	6.2%	14.1%
May 2026(final)	526,352	3.2%	17.9%
June 2026(prelim)	513,610	-2.4%	26.9%

SEAJ can assume no responsibility for the accuracy of the underlying data.

The data are contained in a monthly Billings published by SEAJ that tracks billings worldwide of JAPAN-based manufacturers of equipment used to manufacture semiconductor devices, not billings of the chips themselves.

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